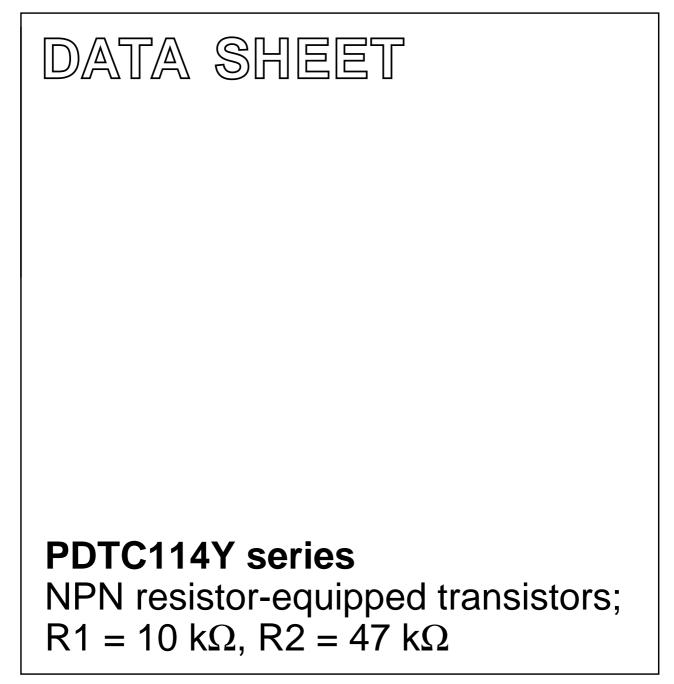
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2003 Sep 10 2004 Aug 17



PDTC114Y series

FEATURES

- Built-in bias resistors
- Simplified circuit design
- Reduction of component count
- Reduced pick and place costs.

APPLICATIONS

- General purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

PRODUCT OVERVIEW

QUICK REFERENCE DATA

| SYMBOL | PARAMETER | TYP. | MAX. | UNIT |
|------------------|------------------------------|------|------|------|
| V _{CEO} | collector-emitter voltage | - | 50 | V |
| lo | output current (DC) | - | 100 | mA |
| R1 | bias resistor | 10 | _ | kΩ |
| R2 | bias resistor | 47 | _ | kΩ |

DESCRIPTION

NPN resistor-equipped transistor (see "Simplified outline, symbol and pinning" for package details).

| | PACKAGE | | | PNP COMPLEMENT | |
|-------------|---------------|--------|--------------------|----------------|--|
| TYPE NUMBER | PHILIPS | EIAJ | | | |
| PDTC114YE | SOT416 | SC-75 | 33 | PDTA114YE | |
| PDTC114YEF | SOT490 | SC-89 | 12 | PDTA114YEF | |
| PDTC114YK | SOT346 | SC-59 | 47 | PDTA114YK | |
| PDTC114YM | SOT883 | SC-101 | DU | PDTA114YM | |
| PDTC114YS | SOT54 (TO-92) | SC-43 | TC114Y | PDTA114YS | |
| PDTC114YT | SOT23 | _ | *27 ⁽¹⁾ | PDTA114YT | |
| PDTC114YU | SOT323 | SC-70 | *30(1) | PDTA114YU | |

Note

- 1. * = p: Made in Hong Kong.
 - * = t: Made in Malaysia.
 - * = W: Made in China.

PDTC114Y series

SIMPLIFIED OUTLINE, SYMBOL AND PINNING

| | SIMPLIFIED OUTLINE AND SYMBOL | | PINNING | | |
|--|---|-------------|------------------------------|--|--|
| TYPE NUMBER | | | DESCRIPTION | | |
| PDTC114YS | | 1 | base | | |
| | | 2 | collector | | |
| | | 3 | emitter | | |
| PDTC114YE PDTC114YEF PDTC114YK PDTC114YT PDTC114YU | 3 1 3 1 2 Top view MDB269 | 1 2 3 | base emitter collector | | |
| PDTC114YM | $2 \boxed{1} \\ bottom view} 3 \\ MHC506 \\ MHC506$ | 1 2 3 | base emitter collector | | |

PDTC114Y series

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

| SYMBOL | PARAMETER CONDITIONS | | MIN. | MAX. | UNIT | |
|------------------|-------------------------------|--------------------------|------|------|------|--|
| V _{CBO} | collector-base voltage | open emitter | _ | 50 | V | |
| V _{CEO} | collector-emitter voltage | open base | _ | 50 | V | |
| V _{EBO} | emitter-base voltage | open collector | - | 10 | V | |
| VI | input voltage | | | | | |
| | positive | | _ | +40 | V | |
| | negative | | _ | -6 | V | |
| lo | output current (DC) | | - | 100 | mA | |
| I _{CM} | peak collector current | | - | 100 | mA | |
| P _{tot} | total power dissipation | T _{amb} ≤ 25 °C | | | | |
| | SOT54 | note 1 | _ | 500 | mW | |
| | SOT23 | note 1 | _ | 250 | mW | |
| | SOT346 | note 1 | _ | 250 | mW | |
| | SOT323 | note 1 | _ | 200 | mW | |
| | SOT416 | note 1 | _ | 150 | mW | |
| | SOT883 | notes 2 and 3 | _ | 250 | mW | |
| | SOT490 | notes 1 and 2 | - | 250 | mW | |
| T _{stg} | storage temperature | | -65 | +150 | °C | |
| Tj | junction temperature | | _ | 150 | °C | |
| T _{amb} | operating ambient temperature | | -65 | +150 | °C | |

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 µm copper strip line.

THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|---------------------|---|---------------|-------|------|
| R _{th j-a} | thermal resistance from junction to ambient | in free air | | |
| | SOT54 | note 1 | 250 | K/W |
| | SOT23 | note 1 | 500 | K/W |
| | SOT346 | note 1 | 500 | K/W |
| | SOT323 | note 1 | 625 | K/W |
| | SOT416 | note 1 | 833 | K/W |
| | SOT883 | notes 2 and 3 | 500 | K/W |
| | SOT490 | notes 1 and 2 | 500 | K/W |

Notes

- 1. Refer to standard mounting conditions.
- 2. Reflow soldering is the only recommended soldering method.
- 3. Refer to SOT883 standard mounting conditions; FR4 with 60 μ m copper strip line.

PDTC114Y series

CHARACTERISTICS

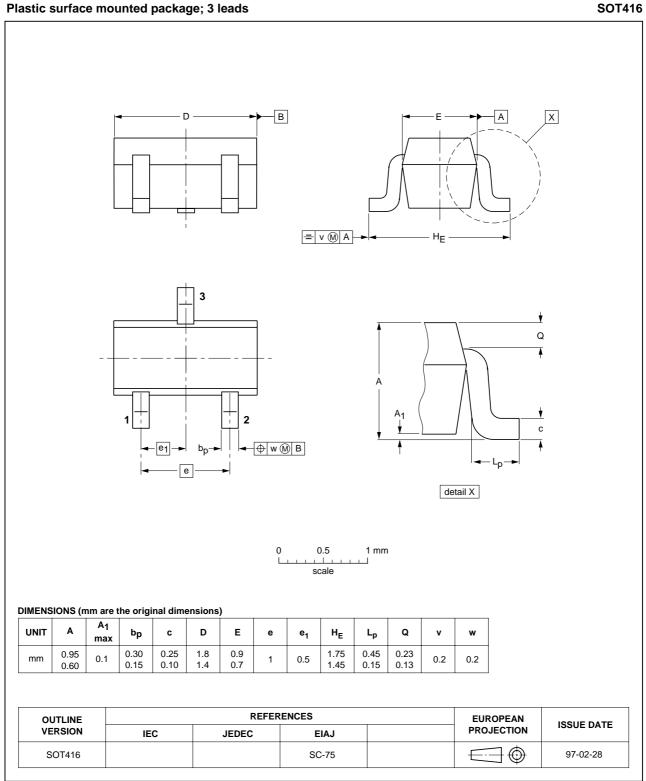
 T_{amb} = 25 °C unless otherwise specified.

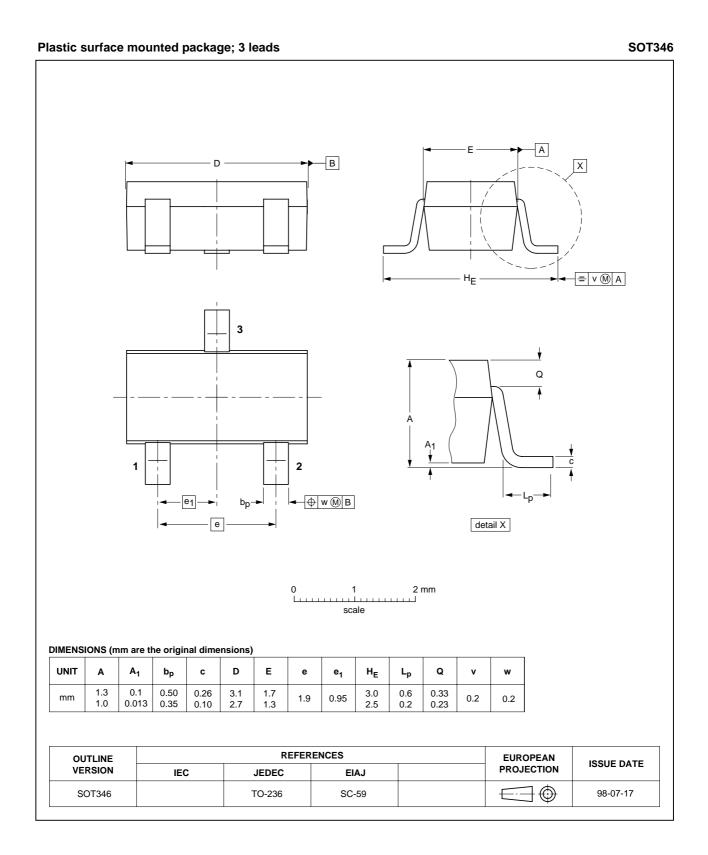
| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---------------------|--------------------------------------|--|------|------|------|------|
| I _{CBO} | collector-base cut-off current | $V_{CB} = 50 \text{ V}; \text{ I}_{E} = 0$ | - | - | 100 | nA |
| I _{CEO} | collector-emitter cut-off current | $V_{CE} = 30 \text{ V}; \text{ I}_{B} = 0$ | - | - | 1 | μA |
| | | $V_{CE} = 30 \text{ V}; \text{ I}_{B} = 0; \text{ T}_{j} = 150 ^{\circ}\text{C}$ | - | - | 50 | μA |
| I _{EBO} | emitter-base cut-off current | $V_{EB} = 5 \text{ V}; I_{C} = 0$ | - | - | 150 | μA |
| h _{FE} | DC current gain | $V_{CE} = 5 V; I_C = 5 mA$ | 100 | - | - | |
| V _{CEsat} | collector-emitter saturation voltage | I _C = 5 mA; I _B = 0.25 mA | - | - | 100 | mV |
| V _{i(off)} | input-off voltage | $I_{C} = 100 \ \mu A; V_{CE} = 5 \ V$ | - | 0.7 | 0.5 | V |
| V _{i(on)} | input-on voltage | $I_{C} = 1 \text{ mA}; V_{CE} = 0.3 \text{ V}$ | 1.4 | 0.8 | _ | V |
| R1 | input resistor | | 7 | 10 | 13 | kΩ |
| R2 R1 | resistor ratio | | 3.7 | 4.7 | 5.7 | |
| C _c | collector capacitance | $I_E = i_e = 0; V_{CB} = 10 V; f = 1 MHz$ | _ | - | 2.5 | pF |

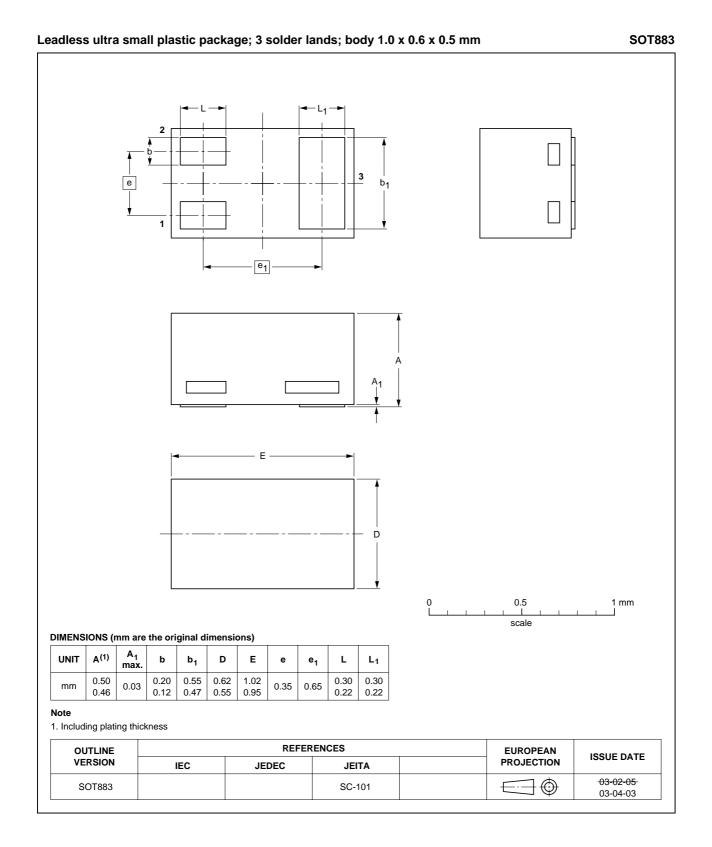
PDTC114Y series

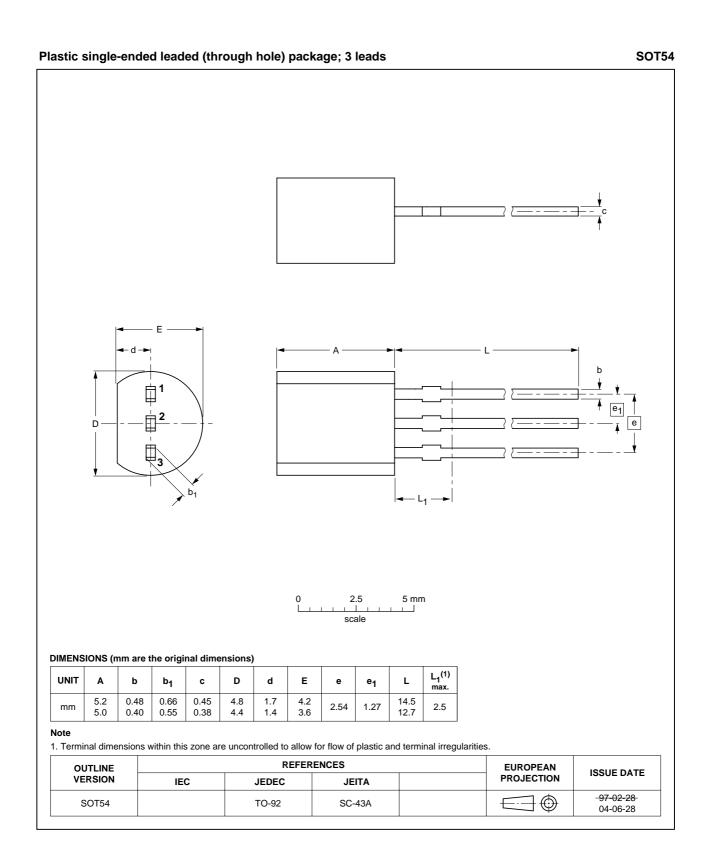
NPN resistor-equipped transistors; $R1 = 10 \text{ k}\Omega$, $R2 = 47 \text{ k}\Omega$

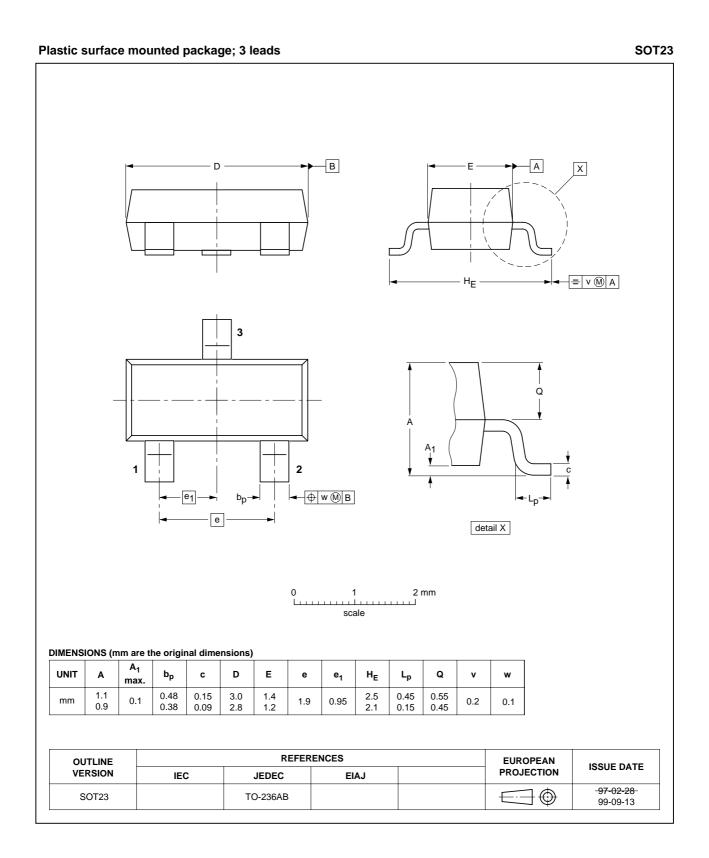
PACKAGE OUTLINES

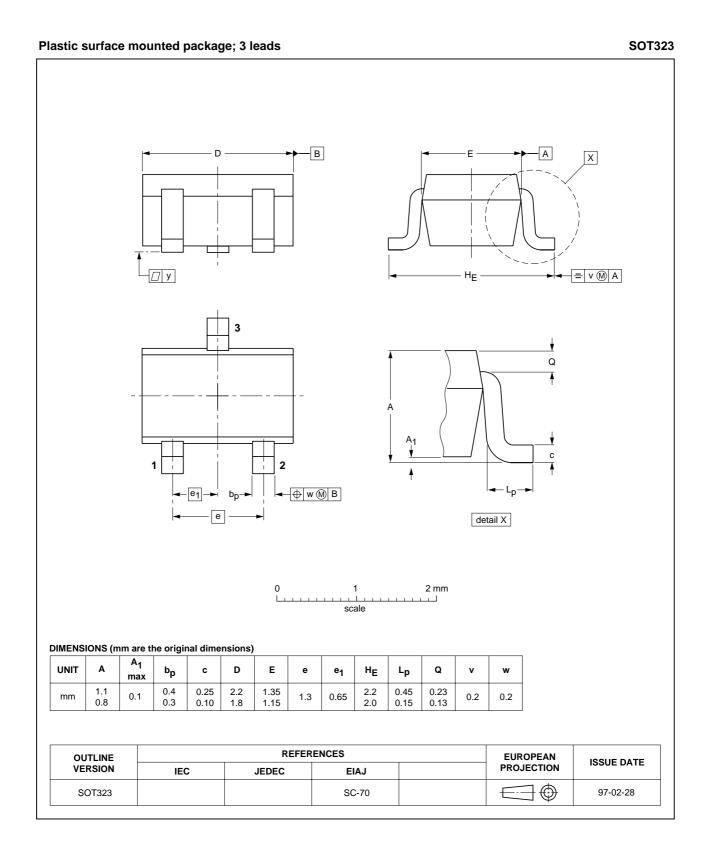


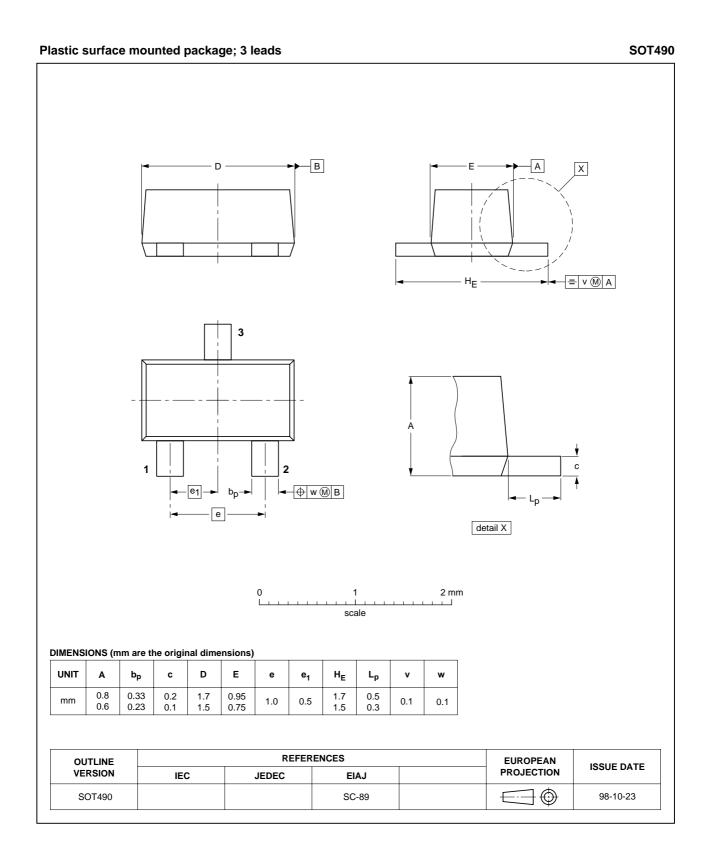












PDTC114Y series

DATA SHEET STATUS

| LEVEL | DATA SHEET STATUS ⁽¹⁾ | PRODUCT STATUS ⁽²⁾⁽³⁾ | DEFINITION |
|-------|-------------------------------------|-------------------------------------|--|
| I | Objective data | Development | This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice. |
| 11 | Preliminary data | Qualification | This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product. |
| | Product data | Production | This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN). |

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Contact information

For additional information please visit http://www.semiconductors.philips.com. Fax: +31 40 27 24825 For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

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